

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

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TOTAL MASS (g) : 0.076089

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.004216 | 1000000 | 55408.9023438 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000176 | 1000000 | 2313.08520508 | | |
| Lead Frame | A42 | Copper (Cu) | 7440-50-8 | 0.000000 | 0 | 0 | | |
| | | Iron (Fe) | 7439-89-6 | 0.014071 | 580000 | 184928.53125 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000000 | 0 | 0 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000000 | 0 | 0 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.010189 | 420000 | 133909.21875 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.024260 | 1000000 | 318837.75 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.001477 | 1000000 | 19409.5703125 | | |
| | | External Plating Total: | | | | 0.001477 | 1000000 | 19409.5703125 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000194 | 1000000 | 2549.65063477 | | |
| Internal Plating Total: | | | | 0.000194 | 1000000 | 2549.65063477 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001155 | 750000 | 15179.6210938 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000385 | 250000 | 5059.87353516 | | |
| Die Attach Total: | | | | 0.001540 | 1000000 | 20239.4941406 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.006606 | 150000 | 86819.5546875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.036114 | 820000 | 474629.3125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.001101 | 25000 | 14469.9257812 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000220 | 5000 | 2891.35668945 | | |
| | | Encapsulation Total: | | | | 0.044041 | 1000000 | 578810.125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000185 | 1000000 | 2431.36791992 | | |
| | | | | | TOTAL MASS (g) : | 0.076089 | | |